



### Features 特性

- Thermal Conductivity 导热
- Low Viscosity 低粘度
- Low Density 低密度
- High Reliability 高可靠性

### Applications 产品应用

- Consumer Electronics 消费电子
- Communication equipment 通讯设备
- Power supply controller 电源控制系统
- Smart Wearable Product 智能穿戴产品

### Operating Requirements 操作要求

- Warm up to room temperature before use 使用前回温到室温
- Any moisture should be immediately wiped off 任何水分应立即擦除
- Cannot be repeatedly frozen 不能反复冷冻

**TUF0060** 是一种具有导热能力的底部填充胶，可以极大地提高芯片的散热效率，增强芯片与 PCB 板之间的粘接力，提升芯片的长期使用可靠性。

**TUF0060** is an adhesive with exceptional thermal conductivity specifically designed for underfill applications in chip packaging. It significantly enhances the chip's heat dissipation efficiency. Additionally, it strengthens the bond between the chip and the PCB, bolstering the long-term reliability of the chip.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
<b>Composition</b> 主要成分	Epoxy Filled with Silica 氧化硅粉体填充环氧树脂	—	—
<b>Color</b> 颜色	Off White 米白色	—	Visual 目视
<b>Thermal Conductivity</b> 导热系数	0.6	W/m·K	ASTM D5470
<b>Viscosity</b> 粘度	5000	mPa·s	CP51, 25°C Speed 20 rpm
<b>Density</b> 密度	1.85	g/cm <sup>3</sup>	ASTM D792
<b>Cure Schedule</b> 固化条件	3min@150°C	—	—
<b>Tg</b> 玻璃化转变温度	110	°C	TMA
<b>CTE</b> 热膨胀系数	50 & 140	ppm/°C	TMA
<b>Storage Modulus</b> 储能模量	5.0	GPa	DMA
<b>Die Shear Strength</b> 粘接强度	10	Kg	3*3mm <sup>2</sup> Si on FR4
<b>Pot Life</b> 使用期	3	day	25°C
<b>Shelf Life</b> 保存期	6	month	-20°C
<b>RoHS Compliance</b> 合规性	YES	—	—

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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